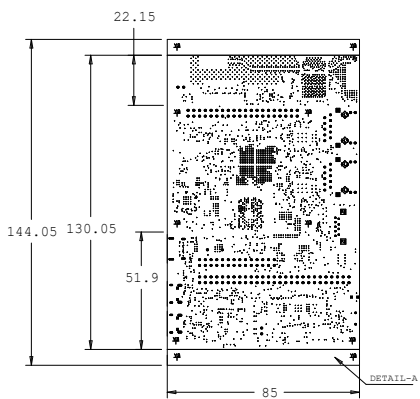


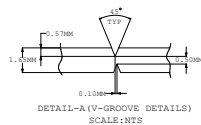
2. FABRICATE PCB IN ACCORDANCE WITH IPC-6102G, CLASS 2; PER IPC-6011.
3. MATERIALS:
- 1. LAMINATE AND PREPREG (B-STAGE) TO BE IN COMPLIANCE WITH IPC-6101/126, (MIN. TO FUL)
 - 2. COPPER FOIL TO BE IN ACCORDANCE WITH IPC-6015G, UNLESS OTHERWISE SPECIFIED, ALL COPPER WEIGHT FOR UNDER SIGNAL LAYERS AND TOP LAYER SHALL BE 35UM (1.0 OZ), FOR TOP LAYER SIGNALS 35UM (1.0 OZ), COPPER WEIGHT IS 18 TO BE CONSIDERED "FINISHED".
 - 3. COPPER FOIL THICKNESS TOLERANCES SHALL BE 10% (IPC 6015B) (MIN. 30-37 AND 3-8).
 - 4. ALL HOLES SHALL BE LOCATED WITHIN 0.1906" DIAMETER OF THE POSITION.
 - 5. LAYEN TO LAYER REGISTRATION SHALL BE 0.0150MM.
 - 6. HOLE AND TRIFIT SHALL NOT EXCEED MORE THAN 0.175 OF THE CIRCLE LENGTH.
 - 7. CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20UM FROM ITS ORIGINAL DATA. INCREASE FOR MATCHING
 - 8. HOLE SHALL APPROVE THE REIFIED WIDTH OF THE HOLE.
 - 9. TRACE WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.
 - 10. BOARD FINISHED SHALL BE ACCORDING TO IPC-6102 CLASS 2.
 - 11. AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.
4. FINISH:
- 1. ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIG, MINIMUM THICKNESS SHALL BE 0.0004 INCHES. SOLDER MASK SHALL BE 3-4 MICRONS THICK. IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
 - 2. ALL EXPOSED NON-CONDUCTIVE PATTERN AREAS SHALL BE ENIG, MINIMUM THICKNESS SHALL BE 0.0004 INCHES. SOLDER MASK SHALL BE 3-4 MICRONS THICK. IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
 - 3. HOLE SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK. ONLY SOLDER MASK IMAGES SHALL BE 0.0004 INCHES THICK. SOLDER MASK SHALL BE 3-4 MICRONS THICK. IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
 - 4. ALL OTHER SOLDER MASK IMAGES SHALL NOT BE ENLARGED. DEFAULT COLOR OF SOLDER MASK SHALL BE RED.
 - 5. SILKSCREEN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE NO ENLARGEMENT OF ANY REDESIGNABLE COMPONENT PART.
 - 6. ALL SILKSCREEN SHALL BE 0.0004 INCHES THICK. SOLDER MASK SHALL BE 3-4 MICRONS THICK. IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
 - 7. IF THE SILK SCREEN FALLS BELOW SOLDERABLE AREAS.
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 - 100. IF THE SILK SCREEN FALLS BELOW SOLDERABLE AREAS.
5. WORKING:
- 1. BOARD SHALL MEET THE REQUIREMENTS OF UL-756 WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE REPRODUCED IN SILKSCREEN.
10. TEST REQUIREMENTS:
- 1. 100% NET LIST ELECTRICAL VERIFICATION USING MISTRAL SUPPLIED 130-354 NET LIST FOR PONES AND SHORTS.
 - 1. TRAVELING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.
 - 2. TEST TRACES SHALL BE 0.0004 INCHES THICK. SOLDER MASK SHALL BE 3-4 MICRONS THICK. IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
 - 3. ALL UNCONNECTED VIA'S SHALL BE INSULATED IF REQUIRED.
 - 4. FINISHED PCB THICKNESS SHALL BE 0.06247 +/-0.01.
 - 5. WITH TRACE WIDTH/SPACING ON BOARD IS 0.00347/0.00347.
 - 6. ENSURE THAT ALL REGISTERED E-FIELD NUMBERS SHALL BE PRINTED ON THE PCB SILKSCREEN.


S/L	TYPE	LAYER	THICKNESS(MIL)	SPACING(MIL)	IMPEDANCE(OHMS)	REF LAYER
01	DGE COUPLED MICROSTRIP	11, 110	4.25	7.15	100	L2, L9
02	DGE COUPLED STRIPLINE	10, 10	3.7	6.8	50	L2/L4/L7/L9
03	DGE COUPLED STRIPLINE	10, 110	4.25	4.5	300	L2, L9
04	DGE COUPLED STRIPLINE	10, 110	4.25	4.5	300	L2, L4/L7/L9
05	STRIPLINE	11, 10	5.8	NA	40	L2/L4/L7/L9
06	STRIPLINE	11, 10	5.8	NA	50	L2/L4/L7/L9
07	MICROSTRIP	11, 110	5.8	NA	50	L4, L9
08	COPLANAR	11	16	14	50	L3
09						
10						

LAYER NAME		FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS
				(INCHES)
PRIMARY SIDE SILKSCREEN				
PRIMARY SIDE SOLDERMASK				
L01	PRIMARY SIDE	1.0x.		0.0037
L02	GROUND-PLANE-1	1.0x.		0.009
L03	INNER-1 SIGNAL-1	1.0x.		0.0066
L04	GROUND-PLANE-2	1.0x.		0.009
L05	POWER-PLANE-1	1.0x.		0.009
L06	POWER-PLANE-2	1.0x.		0.0066
L07	GROUND-PLANE-3	1.0x.		0.005
L08	INNER-2 SIGNAL-1	1.0x.		0.0066
L09	GROUND-PLANE-4	1.0x.		0.004
L10	SECONDARY SIDE	1.0x.		0.0037
SECONDARY SIDE SOLDERMASK				
SECONDARY SIDE SILKSCREEN				



ALL CRATS: TOP TO BOTTOM					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	
•	8.0	+3.0/-3.0	PLATED	2640	
•	28.0	+3.0/-3.0	PLATED	9	
•	32.0	+3.0/-3.0	PLATED	48	
•	36.0	+3.0/-3.0	PLATED	48	
•	40.0	+2.0/-2.0	PLATED	4	
•	40.0	+3.0/-3.0	PLATED	104	
■	66.0	+3.0/-3.0	PLATED	4	
■	66.0	+3.0/-3.0	PLATED	2	
■	32.0	+2.0/-2.0	NON-PLATED	2	
■	32.0	+3.0/-3.0	NON-PLATED	4	
⊙	108.0	+3.0/-3.0	NON-PLATED	10	
⊙	126.0	+3.0/-3.0	NON-PLATED	4	
⊙	48.0x22.0	+3.0/-3.0	PLATED	4	
⊙	52.0x14.0	+2.0/-2.0	PLATED	2	
⊙	68.0x34.0	+3.0/-3.0	PLATED	4	
⊙	82.0x24.0	+2.0/-2.0	PLATED	2	



		MISTRAL SOLUTIONS PVT.LTD., #60, ADARSH REGENT, 100' FEET RING ROAD, DOMLUR EXTENSION, BANGALORE 560 071.		
PCB, SK-AM64 BOARD				
APPROVALS		DATE	DRAWING NO.	REV
THROUGH	UD	15/06/22	PROC100	A
CHECKED	ZA	15/06/22		B
APPROVED	KF	15/06/22		C
SCALE: NONE		FILE NAME:	SHEET 1 OF 17	